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PHOTOCOUPLER PS2732-1, PS2733-1

HIGH COLLECTOR TO EMITTER VOLTAGE SOP MULTI PHOTOCOUPLER

–NEPOC Series–

DESCRIPTION

The PS2732-1 and PS2733-1 are optically coupled isolators containing a GaAs light emitting diode and an NPN silicon darlington-connected phototransistor.

This package is SOP (Small Outline Package) type and has shield effect to cut off ambient light.

It is designed for high density mounting applications.

FEATURES

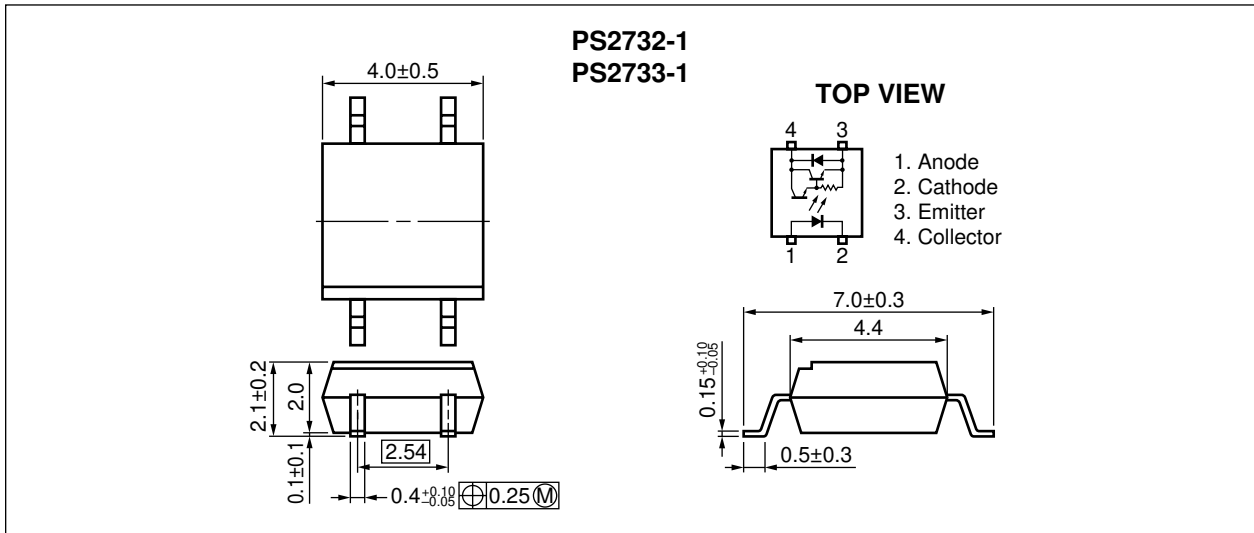
- High isolation voltage ($BV = 2\,500\text{ V r.m.s.}$)
- High collector to emitter voltage ($V_{CEO} = 300\text{ V}$: PS2732-1)
($V_{CEO} = 350\text{ V}$: PS2733-1)
- SOP (Small Outline Package) type
- High current transfer ratio (CTR = 4 000% TYP.)
- Ordering number of taping product : PS2732-1-F3, F4, PS2733-1-F3, F4
- ★ • Safety standards
 - UL approved: File No. E72422
 - BSI approved: File No. 8219/8220
 - CSA approved: File No. CA 101391
 - DIN EN60747-5-2 (VDE0884 Part2) approved (Option)

APPLICATIONS

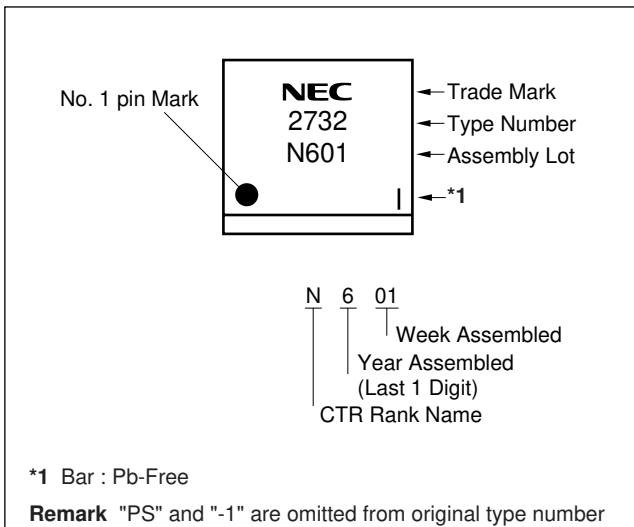
- Hybrid IC
- Telephone/Telegraph Receiver
- FAX

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PACKAGE DIMENSIONS (in millimeters)



★ **MARKING EXAMPLE**



★ **ORDERING INFORMATION**

Part Number	Order Number	Solder Plating Specification	Packing Style	Safety Standard Approval	Application Part Number ^{*1}	
PS2732-1	PS2732-1-A	Pb-Free	Magazine case 100 pcs	Standard products	PS2732-1	
PS2732-1-F3	PS2732-1-F3-A		Embossed Tape 3 500 pcs/reel	(UL, BSI, CSA approved)		
PS2732-1-F4	PS2732-1-F4-A					
PS2732-1-V	PS2732-1-V-A		Magazine case 100 pcs	DIN EN60747-5-2		
PS2732-1-V-F3	PS2732-1-V-F3-A		Embossed Tape 3 500 pcs/reel	(VDE0884 Part2)		
PS2732-1-V-F4	PS2732-1-V-F4-A			Approved (Option)		
PS2733-1	PS2733-1-A			Magazine case 100 pcs	Standard products	PS2733-1
PS2733-1-F3	PS2733-1-F3-A		Embossed Tape 3 500 pcs/reel	(UL, BSI, CSA approved)		
PS2733-1-F4	PS2733-1-F4-A					
PS2733-1-V	PS2733-1-V-A		Magazine case 100 pcs	DIN EN60747-5-2		
PS2733-1-V-F3	PS2733-1-V-F3-A		Embossed Tape 3 500 pcs/reel	(VDE0884 Part2)		
PS2733-1-V-F4	PS2733-1-V-F4-A			Approved (Option)		

*1 For the application of the Safety Standard, following part number should be used.

ABSOLUTE MAXIMUM RATINGS (T_A = 25°C, unless otherwise specified)

Parameter		Symbol	Ratings		Unit
			PS2732-1	PS2733-1	
Diode	Forward Current (DC)	I _F	50		mA
	Reverse Voltage	V _R	6		V
	Power Dissipation Derating	ΔP _D /°C	0.8		mW/°C
	Power Dissipation	P _D	80		mW
	Peak Forward Current* ¹	I _{FP}	1		A
Transistor	Collector to Emitter Voltage	V _{CEO}	300	350	V
	Emitter to Collector Voltage	V _{ECO}	0.3		V
	Collector Current	I _C	150		mA
	Power Dissipation Derating	ΔP _C /°C	1.5		mW/°C
	Power Dissipation	P _C	150		mW
Isolation Voltage* ²		BV	2 500		Vr.m.s.
Operating Ambient Temperature		T _A	-55 to +100		°C
Storage Temperature		T _{stg}	-55 to +150		°C

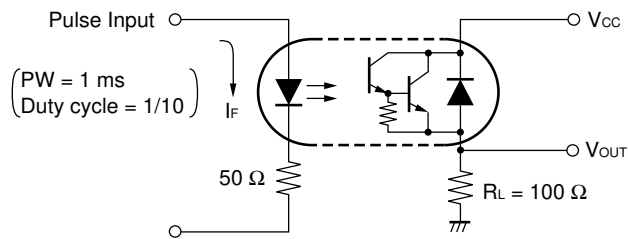
*1 PW = 100 μs, Duty Cycle = 1%

*2 AC voltage for 1 minute at T_A = 25°C, RH = 60% between input and output
 Pins 1-2 shorted together, 3-4 shorted together.

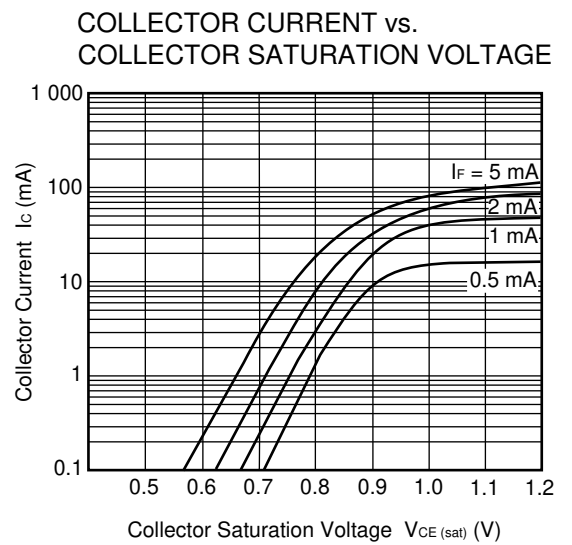
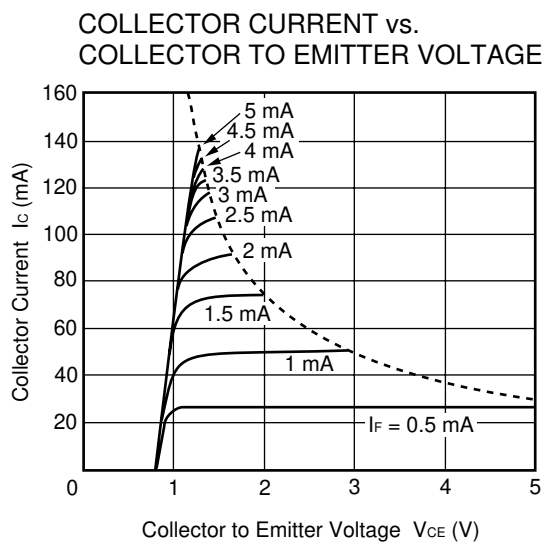
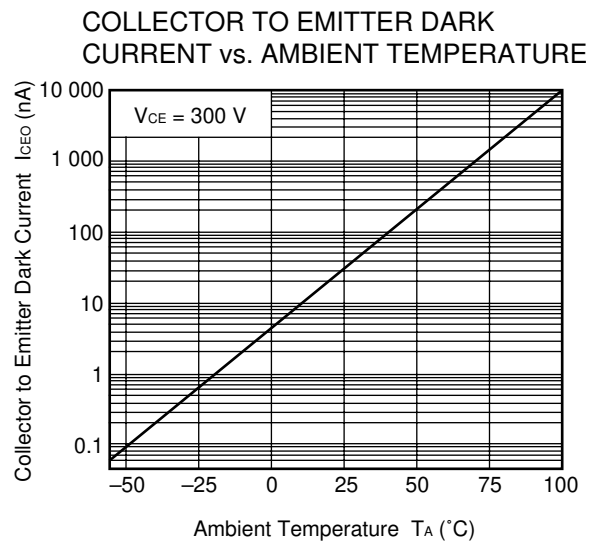
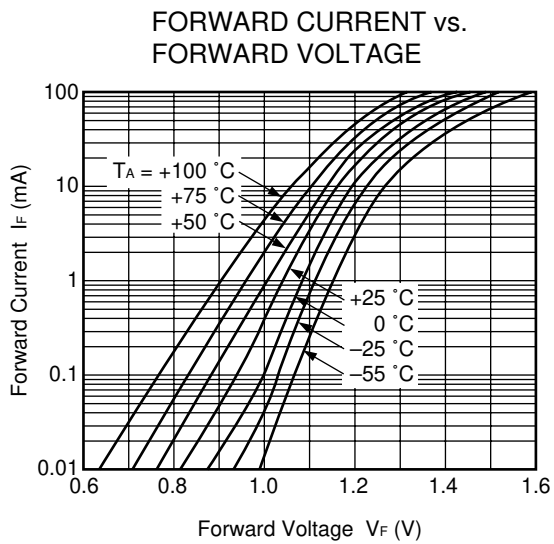
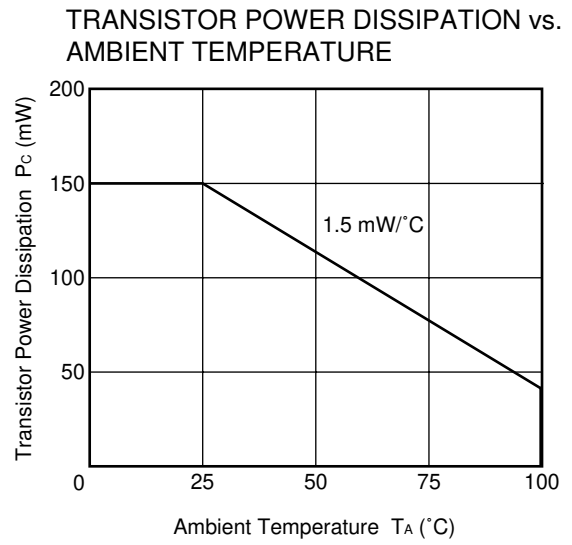
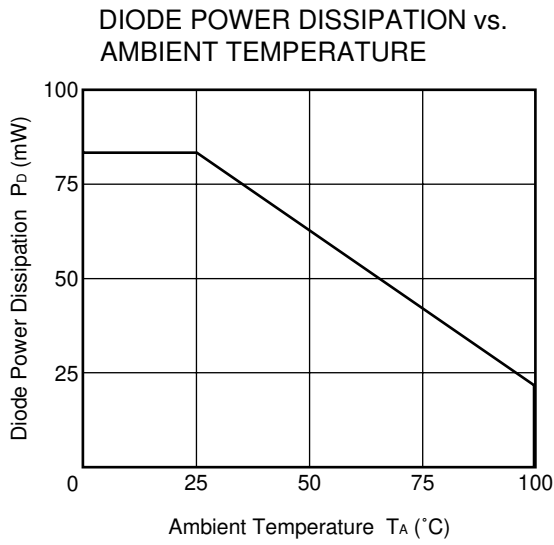
ELECTRICAL CHARACTERISTICS (T_A = 25 °C)

Parameter		Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Diode	Forward Voltage	V _F	I _F = 10 mA		1.15	1.4	V
	Reverse Current	I _R	V _R = 5 V			5	μA
	Terminal Capacitance	C _t	V = 0 V, f = 1 MHz		30		pF
Transistor	Collector to Emitter Dark Current	I _{CEO}	I _F = 0 mA, V _{CE} = 300 V			400	nA
Coupled	Current Transfer Ratio (I _c /I _F)	CTR	I _F = 1 mA, V _{CE} = 2 V	1 500	4 000		%
	Collector Saturation Voltage	V _{CE(sat)}	I _F = 1 mA, I _c = 2 mA			1.0	V
	Isolation Resistance	R _{I-O}	V _{I-O} = 1 kV _{DC}	10 ¹¹			Ω
	Isolation Capacitance	C _{I-O}	V = 0 V, f = 1 MHz		0.4		pF
	Rise Time *1	t _r	V _{CC} = 5 V, I _c = 10 mA, R _L = 100 Ω		100		μs
	Fall Time *1	t _f			100		

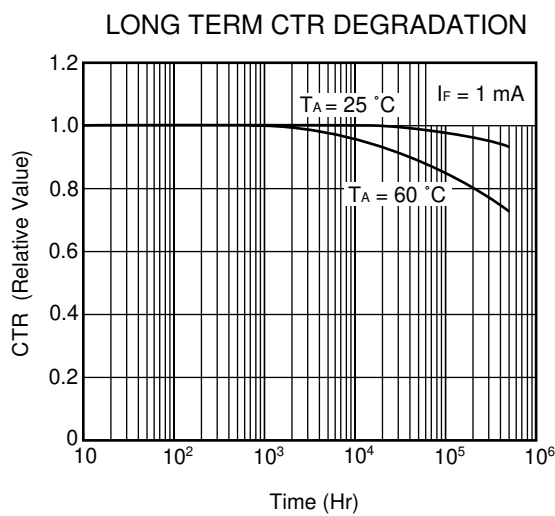
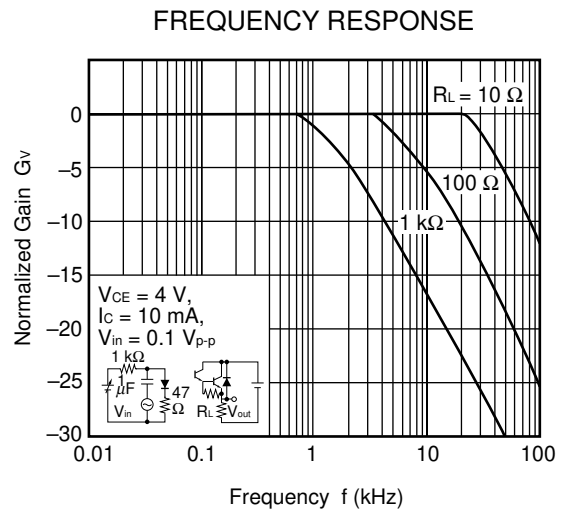
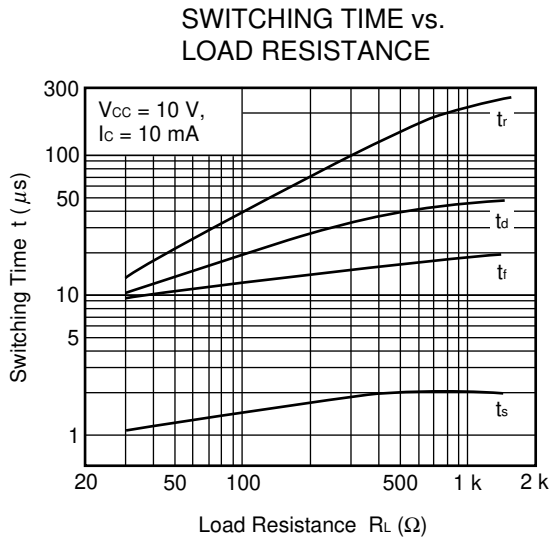
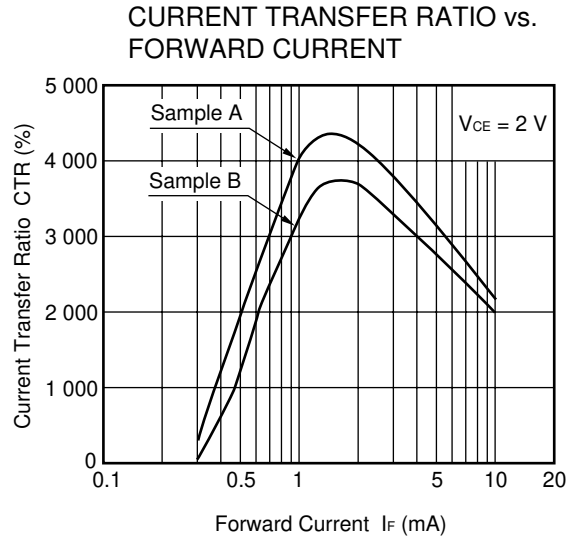
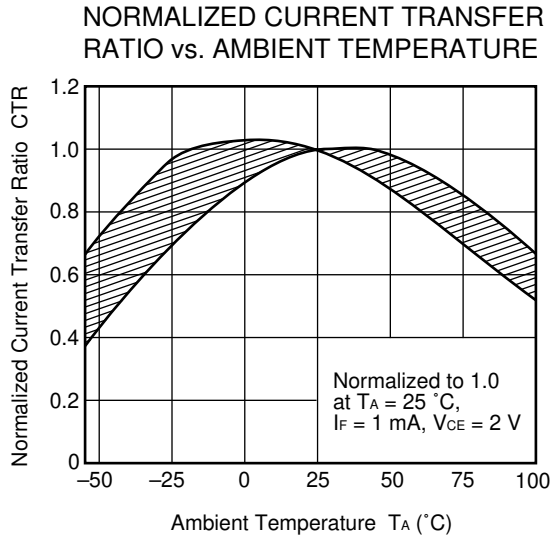
*1 Test circuit for switching time



TYPICAL CHARACTERISTICS ($T_A = 25^\circ\text{C}$, unless otherwise specified)



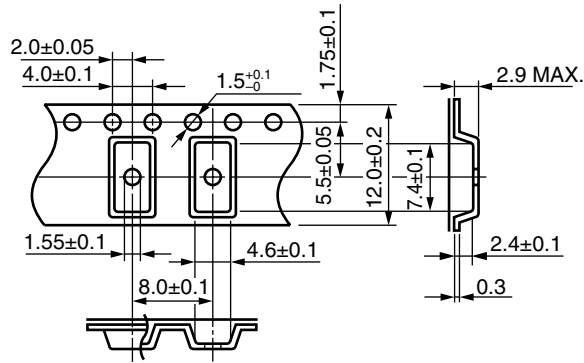
Remark The graphs indicate nominal characteristics.



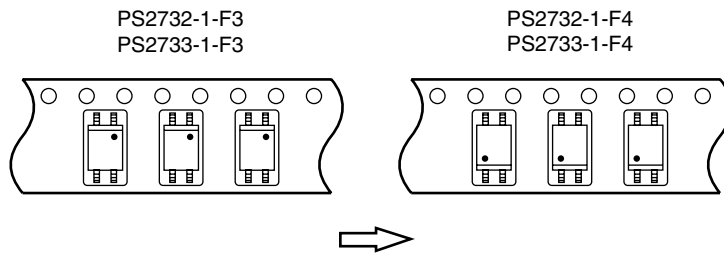
Remark The graphs indicate nominal characteristics.

TAPING SPECIFICATIONS (in millimeters)

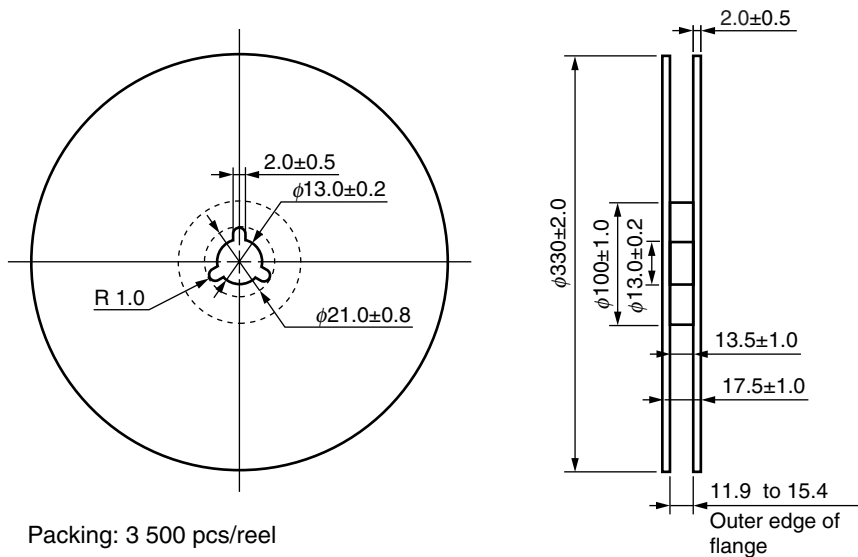
Outline and Dimensions (Tape)



Tape Direction



Outline and Dimensions (Reel)



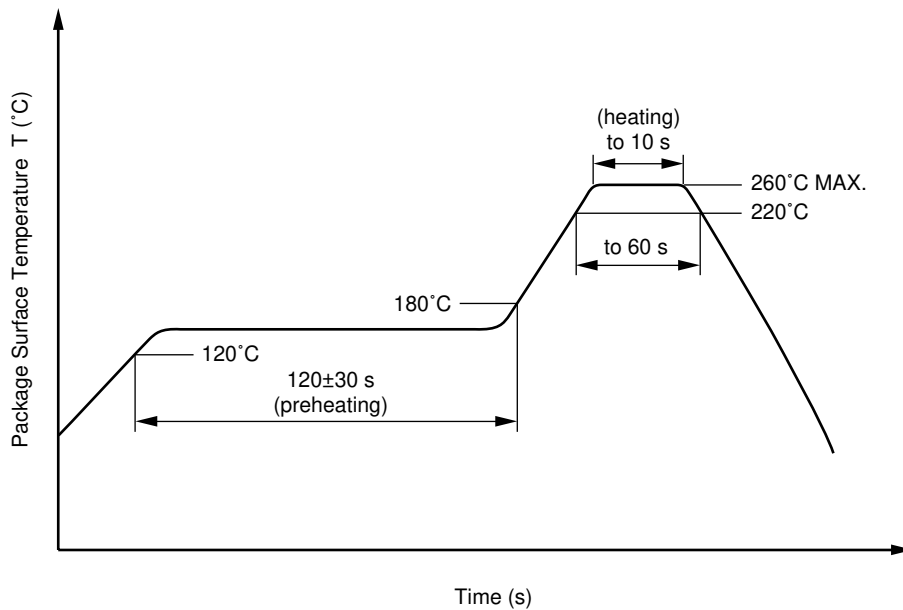
NOTES ON HANDLING

1. Recommended soldering conditions

(1) Infrared reflow soldering

- Peak reflow temperature 260°C or below (package surface temperature)
- Time of peak reflow temperature 10 seconds or less
- Time of temperature higher than 220°C 60 seconds or less
- Time to preheat temperature from 120 to 180°C 120±30 s
- Number of reflows Three
- Flux Rosin flux containing small amount of chlorine (The flux with a maximum chlorine content of 0.2 Wt% is recommended.)

Recommended Temperature Profile of Infrared Reflow



(2) Wave soldering

- Temperature 260°C or below (molten solder temperature)
- Time 10 seconds or less
- Preheating conditions 120°C or below (package surface temperature)
- Number of times One (Allowed to be dipped in solder including plastic mold portion.)
- Flux Rosin flux containing small amount of chlorine (The flux with a maximum chlorine content of 0.2 Wt% is recommended.)

★ **(3) Soldering by soldering iron**

- Peak temperature (lead part temperature) 350°C or below
- Time (each pins) 3 seconds or less
- Flux Rosin flux containing small amount of chlorine (The flux with a maximum chlorine content of 0.2 Wt% is recommended.)

(a) Soldering of leads should be made at the point 1.5 to 2.0 mm from the root of the lead.

(b) Please be sure that the temperature of the package would not be heated over 100°C.

(4) Cautions

- Fluxes

Avoid removing the residual flux with freon-based and chlorine-based cleaning solvent.

2. Cautions regarding noise

Be aware that when voltage is applied suddenly between the photocoupler's input and output or between collector-emitters at startup, the output transistor may enter the on state, even if the voltage is within the absolute maximum ratings.

★ 3. Measurement conditions of current transfer ratios (CTR), which differ according to photocoupler

Check the setting values before use, since the forward current conditions at CTR measurement differ according to product.

When using products other than at the specified forward current, the characteristics curves may differ from the standard curves due to CTR value variations or the like. Therefore, check the characteristics under the actual operating conditions and thoroughly take variations or the like into consideration before use.

USAGE CAUTIONS

1. Protect against static electricity when handling.
2. Avoid storage at a high temperature and high humidity.

SPECIFICATION OF VDE MARKS LICENSE DOCUMENT (VDE0884)

Parameter	Symbol	Speck	Unit
Application classification (DIN VDE 0109) for rated line voltages ≤ 150 Vr.m.s. for rated line voltages ≤ 300 Vr.m.s.		IV III	
Climatic test class (DIN IEC 68 Teil 1/09.80)		55/100/21	
Dielectric strength Maximum operating isolation voltage Test voltage (partial discharge test, procedure a for type test and random test) $U_{pr} = 1.2 \times U_{IORM}, P_d < 5$ pC	U_{IORM} U_{pr}	710 850	V_{peak} V_{peak}
Test voltage (partial discharge test, procedure b for all devices test) $U_{pr} = 1.6 \times U_{IORM}, P_d < 5$ pC	U_{pr}	1 140	V_{peak}
Highest permissible overvoltage	U_{TR}	4 000	V_{peak}
Degree of pollution (DIN VDE 0109)		2	
Clearance distance		> 5	mm
Creepage distance		> 5	mm
Comparative tracking index (DIN IEC 112/VDE 0303 part 1)	CTI	175	
Material group (DIN VDE 0109)		III a	
Storage temperature range	T_{stg}	-55 to +150	°C
Operating temperature range	T_A	-55 to +100	°C
Isolation resistance, minimum value $V_{IO} = 500$ V dc at $T_A = 25$ °C $V_{IO} = 500$ V dc at T_A MAX. at least 100 °C	Ris MIN. Ris MIN.	10^{12} 10^{11}	Ω Ω
Safety maximum ratings (maximum permissible in case of fault, see thermal derating curve) Package temperature Current (input current $I_F, P_{si} = 0$) Power (output or total power dissipation) Isolation resistance $V_{IO} = 500$ V dc at $T_A = 175$ °C (T_{si})	T_{si} I_{si} P_{si} Ris MIN.	150 300 500 10^9	°C mA mW Ω

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M8E 00.4-0110

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